ABSTRACT

Regarding an individuation apparatus for individuating a scaled substrate to manufacture an electronic component, the present invention brings about shortening the delivery period, reducing the footprint, and reducing the cost inc compliance with a specification requested by a user. An individuation apparatus S2 for an electronic component has: a basic unit including a receiving unit A, individuation unit B, and delivery unit C; a cleaning unit D mounted between the individuation unit B and the delivery unit C; and an examination unit E mounted on the cleaning unit D. The individuation unit B is appropriately selected in accordance with the requested specification by the user, and a cutting mechanism used in the individuation unit B has a rotary blade 7, water jet, laser light, wire saw, band saw, etc. The cleaning unit D and examination unit E, both mounted on the basic unit, are each appropriately selected and mounted in accordance with the requested specification by the user. The cleaning unit D and examination unit E are mounted on the basic unit which has the individuation unit B in accordance with the requested specification by the user to form the individuation apparatus S2 for an electronic component.